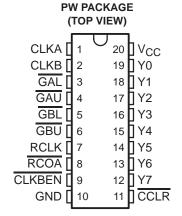
SCLS704A - JULY 2006 - REVISED SEPTEMBER 2007

- Controlled Baseline
 - One Assembly Site
 - One Test Site
 - One Fabrication Site
- Extended Temperature Performance of -55°C to 125°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree[†]
- Can Be Used as Two 16 Bit Counters or a Single 32 Bit Counter
- 2-V to 5.5-V V_{CC} Operation
- Max t_{pd} of 25 ns at 5 V (RCLK to Y)
- Typical V_{OLP} (Output Ground Bounce)
 <0.7 V at V_{CC} = 5 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot) >4.4 V at V_{CC} = 5 V, T_A = 25°C
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 250 mA Per JESD 17

- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.



description/ordering information

The SN74LV8154 is a dual 16 bit binary counter with 3-state output registers, designed for 2-V to 5.5-V V_{CC} operation.

This 16 bit counter (A or B) feeds a 16 bit storage register and each storage register is further divided into an upper byte and lower byte. The GAL, GAU, GBL, and GBU inputs are used to select the byte that needs to be output at Y0–Y7. CLKA is the clock for A counter and CLKB is the clock for B counter. RCLK is the clock for the A and B storage registers. All three clock signals are positive-edge triggered.

A 32 bit counter can be realized by connecting CLKA and CLKB together and by connecting RCOA to CLKBEN.

To ensure the high-impedance state during power up or power down, \overline{GAL} , \overline{GAU} , \overline{GBL} , and \overline{GBU} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION[†]

TA	PACK	AGE [‡]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–55°C to 125°C	TSSOP - PW	Tape and reel	SN74LV8154MPWREP	LV8154ME

[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

[‡] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/packaging.



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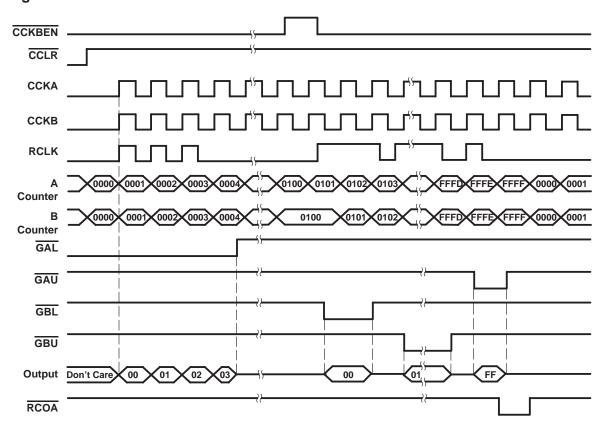


FUNCTION TABLE (each buffer)

	INP	UTS		OUTPUT
GAL	GAU	GBL	GBU	Yn
L	Н	Н	Н	Lower byte in A register
Н	L	Н	Н	Upper byte in A register
Н	Н	L	Н	Lower byte in B register
Н	Н	Н	L	Upper byte in B register
Н	Н	Н	Н	Z

Combinations of GAL, GAU, GBL, and GBU, other than those shown above, are prohibited. If more than one input is L at the same time, the output data (Y0–Y7) may be invalid.

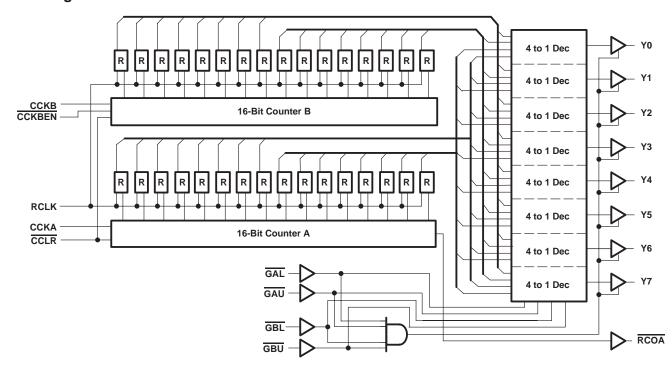
timing diagram





SCLS704A - JULY 2006 - REVISED SEPTEMBER 2007

block diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	\dots -0.5 V to 7 V
Input voltage range, V _I (see Note 1)	-0.5 V to 7 V
Voltage range applied to any output in the high-impedance	
or power-off state, V _O (see Note 1)	–0.5 V to 7 V
Output voltage range, V _O (see Note 1 and Note 2)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I _{IK} (V _I < 0 V)	–20 mA
Output clamp current, I _{OK} (V _O < 0 V)	–50 mA
Continuous output current, I_O ($V_O = 0$ V to V_{CC})	
Continuous current through V _{CC} or GND	±70 mA
Package thermal impedance, θ _{JA} (see Note 3):	83°C/W
Storage temperature range, T _{stg}	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 5.5 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.



SN74LV8154-EP DUAL 16 BIT BINARY COUNTER WITH 3-STATE OUTPUT REGISTERS

SCLS704A - JULY 2006 - REVISED SEPTEMBER 2007

recommended operating conditions (see Note 4)

			VCC	MIN	MAX	UNIT	
VCC	Supply voltage			2	5.5	V	
			2 V	1.5			
V_{IH}	High-level input voltage		3 V to 3.6 V	V _{CC} ×0.7		V	
		4.5 V to 5.5 V	V _{CC} ×0.7				
			2 V		0.5		
۷ _{IL}	Low-level input voltage		3 V to 3.6 V		V _{CC} ×0.3	V	
		4.5 V to 5.5 V		V _{CC} ×0.3			
٧ _I	Input voltage			0	5.5	V	
.,	0	High or low state		0	Vcc	.,	
VO	Output voltage	3-state		0	5.5	V	
			2 V		-50	μΑ	
	High-level output current	Yn outputs	3 V to 3.6 V		-6		
			4.5 V to 5.5 V		-12	mA	
ЮН			2 V		-50	μΑ	
		RCOA	3 V to 3.6 V		-6		
			4.5 V to 5.5 V		-12	mA	
			2 V		50	μΑ	
		Yn outputs	3 V to 3.6 V		6		
	Level bear level and and assessed		4.5 V to 5.5 V	12		mA	
lOL	Low-level output current		2 V		50	μΑ	
		RCOA	3 V to 3.6 V		6		
			4.5 V to 5.5 V		12	mA	
		•	3 V to 3.6 V		100	0.1	
Δt/Δν	Input transition rise or fall rate		4.5 V to 5.5 V		20	ns/V	
TA	Operating free-air temperature			-55	125	°C	

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. See the TI application report, *Implications* of Slow or Floating CMOS Inputs, literature number SCBA004.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	VCC	MIN	TYP	MAX	UNIT
		$I_{OH} = -50 \mu\text{A}$	2 V	1.9			
	Yn	$I_{OH} = -6 \text{ mA}$	3 V	2.48	2.48		
.,		$I_{OH} = -12 \text{ mA}$	4.5 V	3.8			V
VOH		$I_{OH} = -50 \mu\text{A}$	2 V	1.9			V
	RCOA	$I_{OH} = -6 \text{ mA}$	3 V	2.48			
		$I_{OH} = -12 \text{ mA}$	4.5 V	3.8			
		$I_{OL} = 50 \mu A$	2 V			0.1	
	Yn	$I_{OL} = 6 \text{ mA}$	3 V			0.44	
		$I_{OL} = 12 \text{ mA}$	4.5 V			0.55	.,
VOL	RCOA	$I_{OL} = 50 \mu A$	2 V			0.1	V
		$I_{OL} = 6 \text{ mA}$	3 V			0.44	
		$I_{OL} = 12 \text{ mA}$	4.5 V			0.55	
lį		$V_I = 5.5 \text{ V or GND}$	0 V to 5.5 V			±1	μΑ
loz		$V_O = V_{CC}$ or GND	5.5 V			±5	μΑ
Icc		$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			20	μΑ
l _{off}		V_I or $V_O = 0 V$ to 5.5 V	0 V			5	μΑ
Ci		$V_I = V_{CC}$ or GND	5 V 3			pF	
Co		$V_O = V_{CC}$ or GND	5 V		5	·	pF

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

			MIN	MAX	UNIT
	Dulas duration	CLKA, CLKB, and RCLK high or low	10		
t _W	Pulse duration	CCLR low	22		ns
		CLKBEN low before CLKB↑	13		
		CCLR high (inactive) before CLKA↑ or CLKB↑			
t _{su}	Setup time	CLKA↑ or CLKB↑ before RCLK↑	13		ns
		RCLK [↑] before GAL, GAU, GBL, or GBU low	13		
		GAL, GAU, GBL, or GBU high (inactive) before RCLK↑	13		
4.	Hald the a	CLKBEN low after CLKB↑	0		
th	Hold time	CLKA or CLKB after RCLK	0		ns
t _z †	Z-period	GAL, GAU, GBL, and GBU all high before one of them switches low	200		ns

 $[\]dagger t_Z$ condition: $C_L = 50$ pF, $R_L = 1$ k Ω



SN74LV8154-EP DUAL 16 BIT BINARY COUNTER WITH 3-STATE OUTPUT REGISTERS

SCLS704A - JULY 2006 - REVISED SEPTEMBER 2007

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

			MIN	MAX	UNIT
	Dulas dematics	CLKA, CLKB, and RCLK high or low	10		
t _W	Pulse duration	CCLR low	20		ns
		CLKBEN low before CLKB↑	10		
		CCLR high (inactive) before CLKA↑ or CLKB↑	10		
t _{Su} Setup time	Setup time	CLKA↑ or CLKB↑ before RCLK↑	10		ns
		RCLK↑ before GAL, GAU, GBL, or GBU low	10		
		GAL, GAU, GBL, or GBU high (inactive) before RCLK↑	10		
	Hold time	CLKBEN low after CLKB↑	0		20
th	noid time	CLKA or CLKB after RCLK	0		ns
t _Z †	Z period	GAL, GAU, GBL, and GBU all high before one of them switches low	200	·	ns

 $[\]dagger$ t_Z condition: C_L = 50 pF, R_L = 1 k Ω

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T _A = 25°C	MIN	MAX	UNIT
FARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	TYP	IVIIIV	WIAA	UNIT
fMAX			$C_L = 50 pF$		25		MHz
	RCLK	Y		25	1	42	
^t pd	CLKA	RCOA		28	1	46	ns
t _{PLH}	CCLR	RCOA	C _L = 50 pF	20	1	35	ns
t _{en}	GAL, GAU, GBL, GBU	Υ		30	1	50	ns
^t dis	GAL, GAU, GBL, GBU	Υ		14	1	24	ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO	LOAD	T _A = 25°C	MIN	MAX	UNIT
	(INPUT)	(OUTPUT)	CAPACITANCE	TYP			· · · · ·
fMAX			$C_L = 50 pF$		25		MHz
	RCLK	Υ		16	1	27	
^t pd	CLKA	RCOA		17	1	28	ns
^t PLH	CCLR	RCOA	C _L = 50 pF	13	1	21	ns
t _{en}	GAL, GAU, GBL, GBU	Υ		18	1	30	ns
^t dis	GAL, GAU, GBL, GBU	Υ		9	1	16	ns

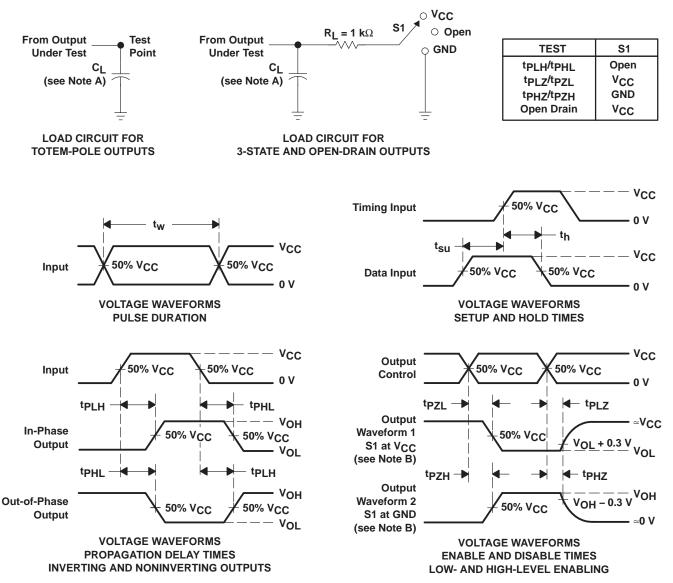
noise characteristics, V_{CC} = 5 V, C_L = 50 pF

	DADAMETED	T _A = 25°C	UNIT			
	PARAMETER					
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}	0.7	V			
V _{OL(V)}	Quiet output, minimum dynamic VOL	-0.75	V			
V _{OH(V)}	Quiet output, minimum dynamic VOH	4.4	V			

operating characteristics, V_{CC} = 5 V, T_A = 25 $^{\circ}C$

	PARAMETER		TYP	UNIT		
C _{pd}	Power dissipation capacitance	C _L = No load,	CCLK = 10 MHz,	RCLK = 1 MHz	56	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f \leq 3$ ns, $t_f \leq 3$ ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpHL and tpLH are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuits and Voltage Waveforms



11-Nov-2025 www.ti.com

PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
SN74LV8154MPWREP	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LV8154ME
SN74LV8154MPWREP.A	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LV8154ME
V62/06662-01XE	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LV8154ME

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF SN74LV8154-EP:

Catalog: SN74LV8154

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



PACKAGE OPTION ADDENDUM

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NOTE: Qualified Version Definitions:

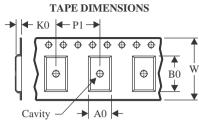
 $_{\bullet}$ Catalog - TI's standard catalog product

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV8154MPWR	EP TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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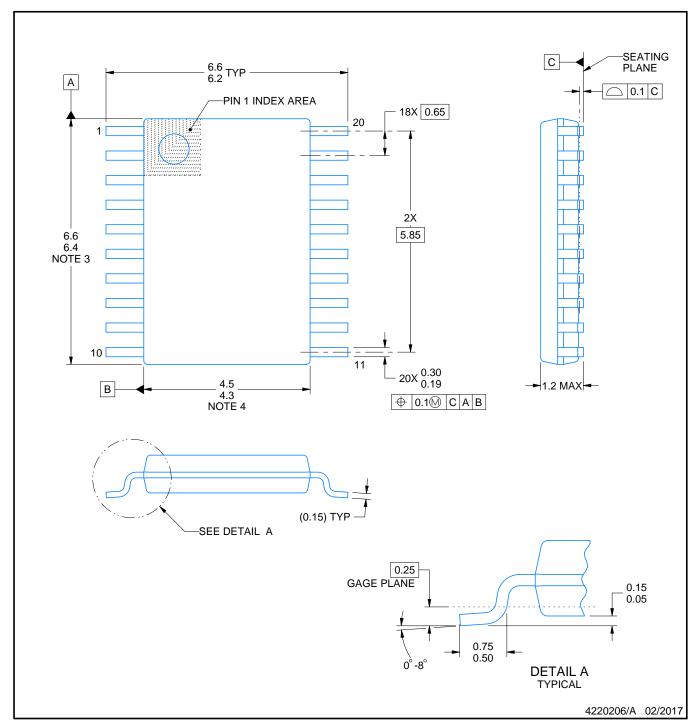


*All dimensions are nominal

Ì	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ı	SN74LV8154MPWREP	TSSOP	PW	20	2000	353.0	353.0	32.0



SMALL OUTLINE PACKAGE



NOTES:

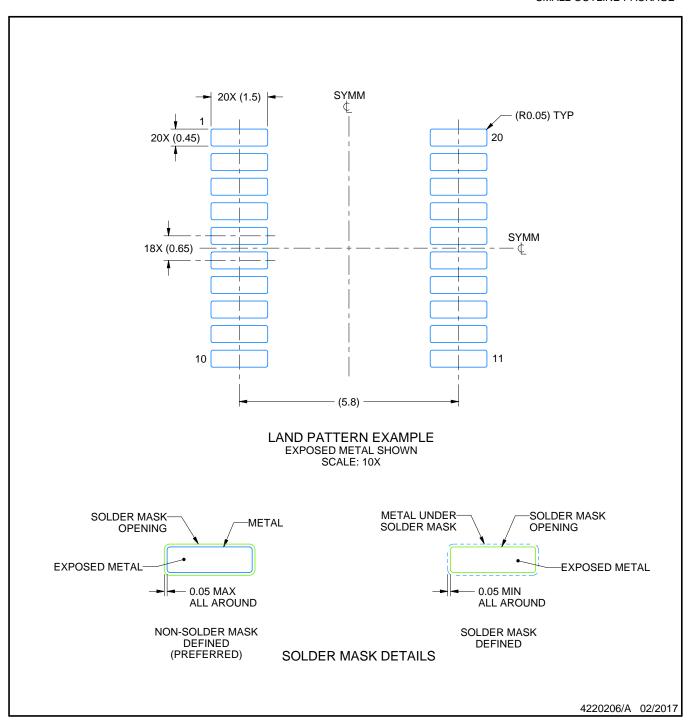
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



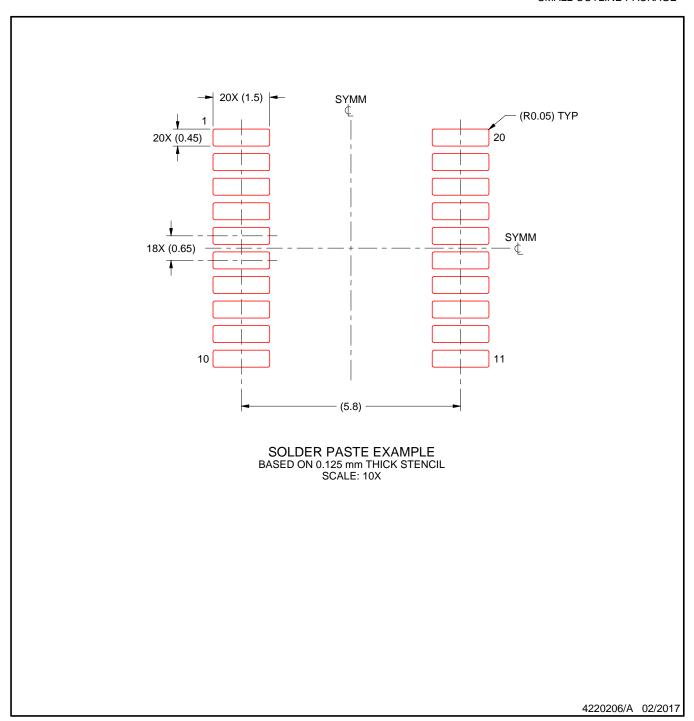
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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